

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit: To Be Assigned
Examiner: To Be Assigned

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1c979 U.S. PTO
10/022268
12/20/01

In re PATENT APPLICATION of

Applicant(s) : TERUI et al.

Appln. No. : To Be Assigned

Filed : December 20, 2001

For : SEMICONDUCTOR PACKAGE AND
METHOD OF FABRICATING SAME

Atty. Dkt. : OKI 286

INFORMATION
DISCLOSURE
STATEMENT

Commissioner for Patents
Washington, D.C. 20231

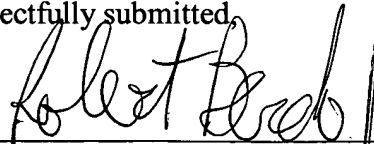
Sir:

This is an information disclosure statement submitted in compliance with the timing requirements of 37 C.F.R. §1.97(b)(1).

Attached are copies of a U.S. patent and a Japanese patent. The relevance of the Japanese patent can be gleaned from the attached English-language Abstract. The patents are listed on the attached Form PTO-1449.

Since this Information Disclosure Statement is being filed with the application, no certification or fee is required, and the requirements of 37 C.F.R. §§1.97 and 1.98 are deemed to be fully met as to the document submitted. Consideration of the submitted document is respectfully requested.

Respectfully submitted,



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December 20, 2001
Date

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